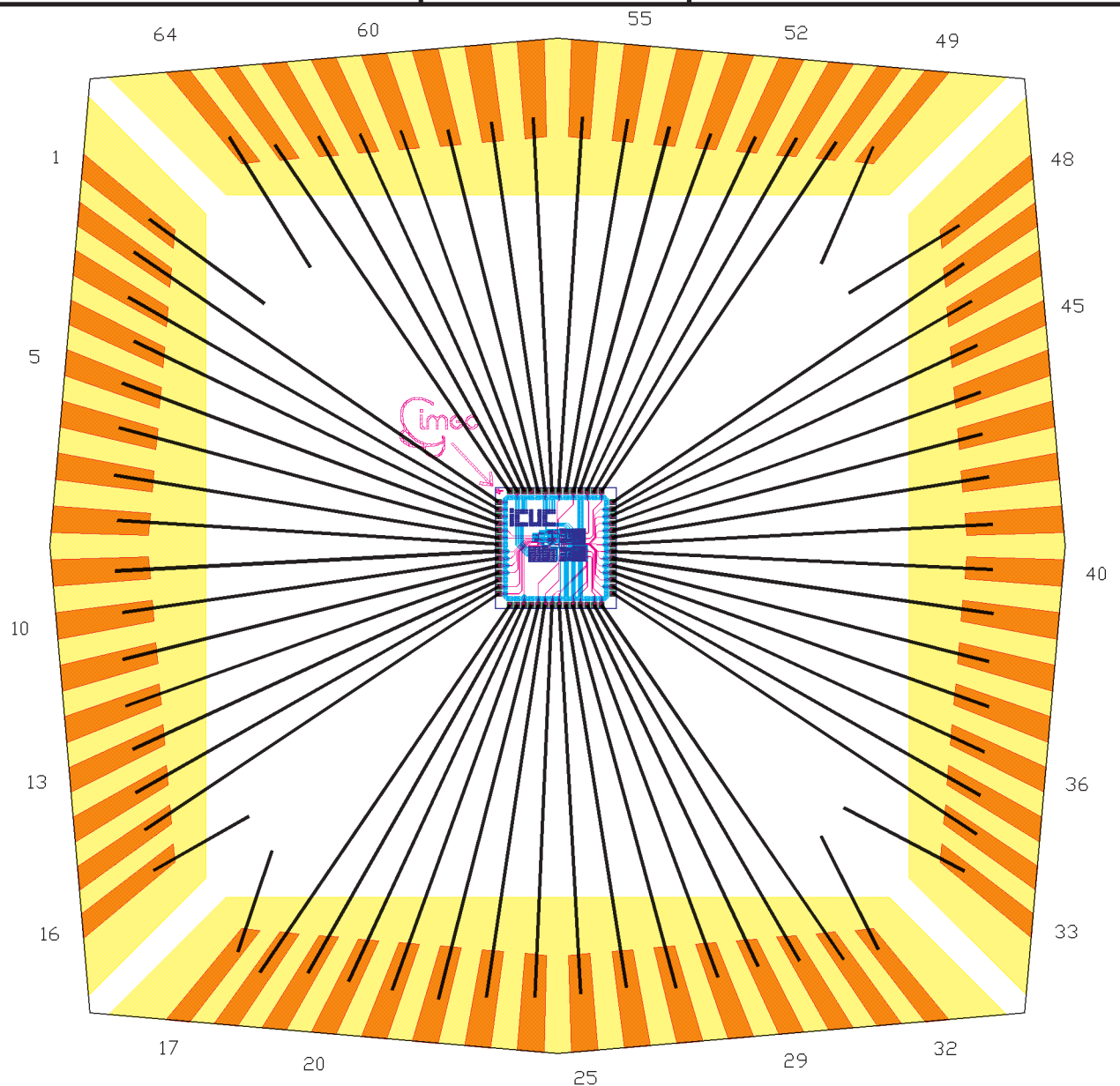


Request: UCC

Pitch: 0.8 mm
Body size: 14 x 14 mm
Footprint: 3.2 mm

CQFP64
Ceramic Quad Flat Pack



Minimum bondpad pitch: 90um
Comment: Minimum bondpad size: 65umx65um
Die thickness: 11mil

MPW: EP4114

Date: April 23, 2014

Scale

Die: BeanV2

Size incl scribe: 1565umx1565um

10

Qty packaged: 10

Lid: Taped ☐ Sealed ☒ Glued ☐ Glass ☐

Qty naked: What remains

Die Attach: Default

Wire: Default

Info:



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